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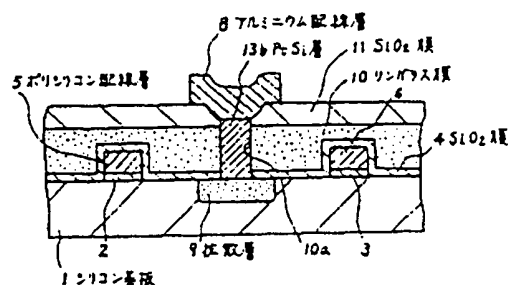
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TITLE : MANUFACTURE OF
SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To improve the reliability of an interconnection, by forming a first noncorrosive conductor layer at a part, which is contacted with a first insulating film so that the second conductor layer is not corroded with impurities included in the first insulating film.

CONSTITUTION: A first noncorrosive conductor layer 13b with respect to impurities included in an insulating film 10 is formed on a hole part 10a of a first insulating film 10 on a part to be connected 9. The part to be connected 9 and a second conductor layer 8 are connected through the conductor layer 13b. Then, the conductor layer 8 is not contacted with the insulating film 10, and the conductor layer 8 is not corroded with the impurities included in the insulating film 10. Thus, the reliability of an interconnection is improved.

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